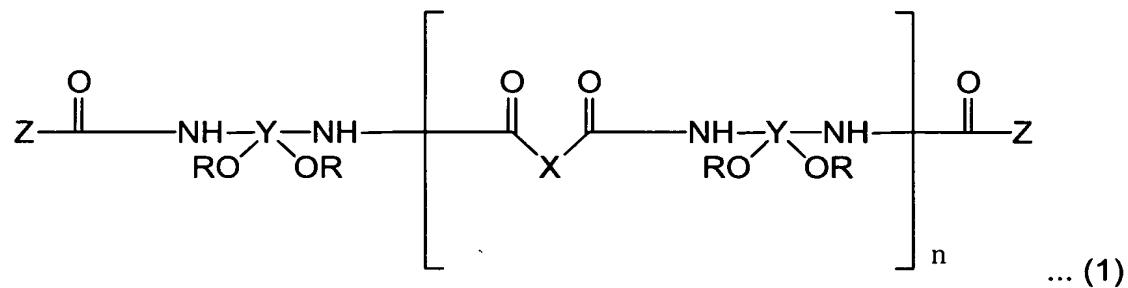


AMENDMENTS TO THE CLAIMS

This following listing of claims replaces all prior listings, and all prior versions, of claims in the application:

LISTING OF CLAIMS:

1. (Original) A photosensitive resin composition comprising:
 - (A) a heat-resistant polymer represented by general formula (1)



where X represents a divalent organic group; Y represents a tetravalent organic group; Z represents a cyclic compound group free of reactive unsaturated bonds; R represents hydrogen or a monovalent organic group; and n is an integer of 2 to 500 and represents the number of repeating units of the polymer;

- (B) a photoreactive compound; and
 - (C) a solvent.

2. (Original) The photosensitive resin composition according to claim 1, wherein at least one of the organic groups X and Y is an aromatic group.
 3. (Original) The photosensitive resin composition according to claim 1, wherein

the cyclic compound group Z is a compound group having an alicyclic structure.

4. (Original) The photosensitive resin composition according to claim 2, wherein the cyclic compound group Z is a compound group having an alicyclic structure.

5. (Original) The photosensitive resin composition according to claim 3, wherein the compound group having an alicyclic structure has 3 or 4 carbon atoms.

6. (Original) The photosensitive resin composition according to claim 4, wherein the compound group having an alicyclic structure has 3 or 4 carbon atoms.

7. (Original) The photosensitive resin composition according to claim 1, wherein the divalent organic group represented by X comprises at least one divalent group derived from 3-fluoroisophthalic acid, 2-fluoroisophthalic acid, 3-fluorophthalic acid, 2-fluorophthalic acid, 2,4,5,6-tetrafluoroisophthalic acid, 3,4,5,6-tetrafluorophthalic acid, 4,4'-hexafluoroisopropylidenediphenyldicarboxylic acid, perfluorosuberic acid, 2,2'-bis(trifluoromethyl)-4,4'-biphenyleneddicarboxylic acid, terephthalic acid, isophthalic acid, 4,4'-oxydiphenyldicarboxylic acid, 5-nitroisophthalic acid, 1,4-naphthalenedicarboxylic acid, 2,6-naphthalenedicarboxylic acid, and 4,4'-biphenyldicarboxylic acid.

8. (Original) The photosensitive resin composition according to claim 1, wherein the tetravalent organic group represented by Y comprises at least one divalent group

derived from 4,4'-diamino-3,3'-dihydroxybiphenyl, 2,2'-bis(3-amino-4-hydroxyphenyl)propane, and 2,2'-bis(3-amino-4-hydroxyphenyl)hexafluoropropane.

9. (Original) The photosensitive resin composition according to claim 1, wherein Z comprises at least one group selected from the group consisting of cyclopropyl, cyclobutyl, 2-phenyl-1-cyclopropyl, 1-phenyl-1-cyclopropyl, 1-benzocyclobutenyl, 2-methylcyclopropenyl, 1-hydroxy-1-cyclopropyl, 1-carboxy-1-cyclopropyl, and 1-carboxy-1-cyclobutyl.

10. (Original) The photosensitive resin composition according to claim 1, wherein the heat-resistant polymer has a weight average molecular weight in the range of 5,000 to 80,000.

11. (Original) A process for forming a relief pattern, comprising:
applying the photosensitive resin composition according to claim 1 to a support substrate and drying the composition applied to form a photosensitive resin film;
subjecting the dried photosensitive resin film to exposure;
subjecting the exposed photosensitive resin film to development using an alkaline aqueous solution; and
subjecting the developed photosensitive resin film to heating treatment.

12. (Original) An electronic component having an electronic device including at

least an interlayer dielectric film layer and a surface protecting film layer,
wherein at least one of the interlayer dielectric film layer and the surface
protecting film layer comprises a resin film formed from the photosensitive resin
composition according to claim 1.

13. (Currently Amended) The An electronic component having an electronic
device including at least an interlayer dielectric film and a surface protecting layer,
wherein at least one of the interlayer dielectric film and the surface protecting
layer comprises a resin film, and device according to claim 12, wherein the resin film
comprises a patterned film formed by the process according to claim 11.